

# HOSTAFORM® XGC15-LW01 XAP®

## HOSTAFORM®

Hostaform® XGC15-LW01 is an injection molding grade reinforced with approximately 15% glass fibers and tribological modification for sliding applications requiring low friction and wear.

### Product information

|                      |            |           |
|----------------------|------------|-----------|
| Resin Identification | POM-GF15   | ISO 1043  |
| Part Marking Code    | >POM-GF15< | ISO 11469 |

### Rheological properties

|                              |                            |                 |
|------------------------------|----------------------------|-----------------|
| Melt volume-flow rate        | 1.1 cm <sup>3</sup> /10min | ISO 1133        |
| Temperature                  | 190 °C                     |                 |
| Load                         | 2.16 kg                    |                 |
| Moulding shrinkage, parallel | 1.1 %                      | ISO 294-4, 2577 |
| Moulding shrinkage, normal   | 0.9 %                      | ISO 294-4, 2577 |

### Typical mechanical properties

|                                      |                       |              |
|--------------------------------------|-----------------------|--------------|
| Tensile modulus                      | 5400 MPa              | ISO 527-1/-2 |
| Tensile stress at break, 5mm/min     | 105 MPa               | ISO 527-1/-2 |
| Tensile strain at break, 5mm/min     | 3.8 %                 | ISO 527-1/-2 |
| Flexural modulus                     | 5100 MPa              | ISO 178      |
| Charpy impact strength, 23°C         | 50 kJ/m <sup>2</sup>  | ISO 179/1eU  |
| Charpy notched impact strength, 23°C | 9.5 kJ/m <sup>2</sup> | ISO 179/1eA  |
| Poisson's ratio                      | 0.35 <sup>[C]</sup>   |              |

[C]: Calculated

### Thermal properties

|  |           |                |
|--|-----------|----------------|
| Melting temperature, 10°C/min                            | 166 °C    | ISO 11357-1/-3 |
| Temperature of deflection under load, 1.8 MPa            | 160 °C    | ISO 75-1/-2    |
| Coefficient of linear thermal expansion (CLTE), parallel | 40 E-6/K  | ISO 11359-1/-2 |
| Coefficient of linear thermal expansion (CLTE), normal   | 110 E-6/K | ISO 11359-1/-2 |

### Physical/Other properties

|         |                        |          |
|---------|------------------------|----------|
| Density | 1460 kg/m <sup>3</sup> | ISO 1183 |
|---------|------------------------|----------|

### Injection

|                                 |              |
|---------------------------------|--------------|
| Drying Recommended              | no           |
| Drying Temperature              | 100 °C       |
| Drying Time, Dehumidified Dryer | 3 - 4 h      |
| Processing Moisture Content     | ≤0.2 %       |
| Melt Temperature Optimum        | 200 °C       |
| Min. melt temperature           | 190 °C       |
| Max. melt temperature           | 210 °C       |
| Screw tangential speed          | ≤0.3 m/s     |
| Mold Temperature Optimum        | 100 °C       |
| Min. mould temperature          | 80 °C        |
| Max. mould temperature          | 120 °C       |
| Hold pressure range             | 60 - 120 MPa |

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Back pressure 2 MPa  
Ejection temperature 130 °C

### Characteristics

Processing Injection Moulding  
Special characteristics Low wear / Low friction, Low emissions

### Additional information

Processing Notes

#### Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

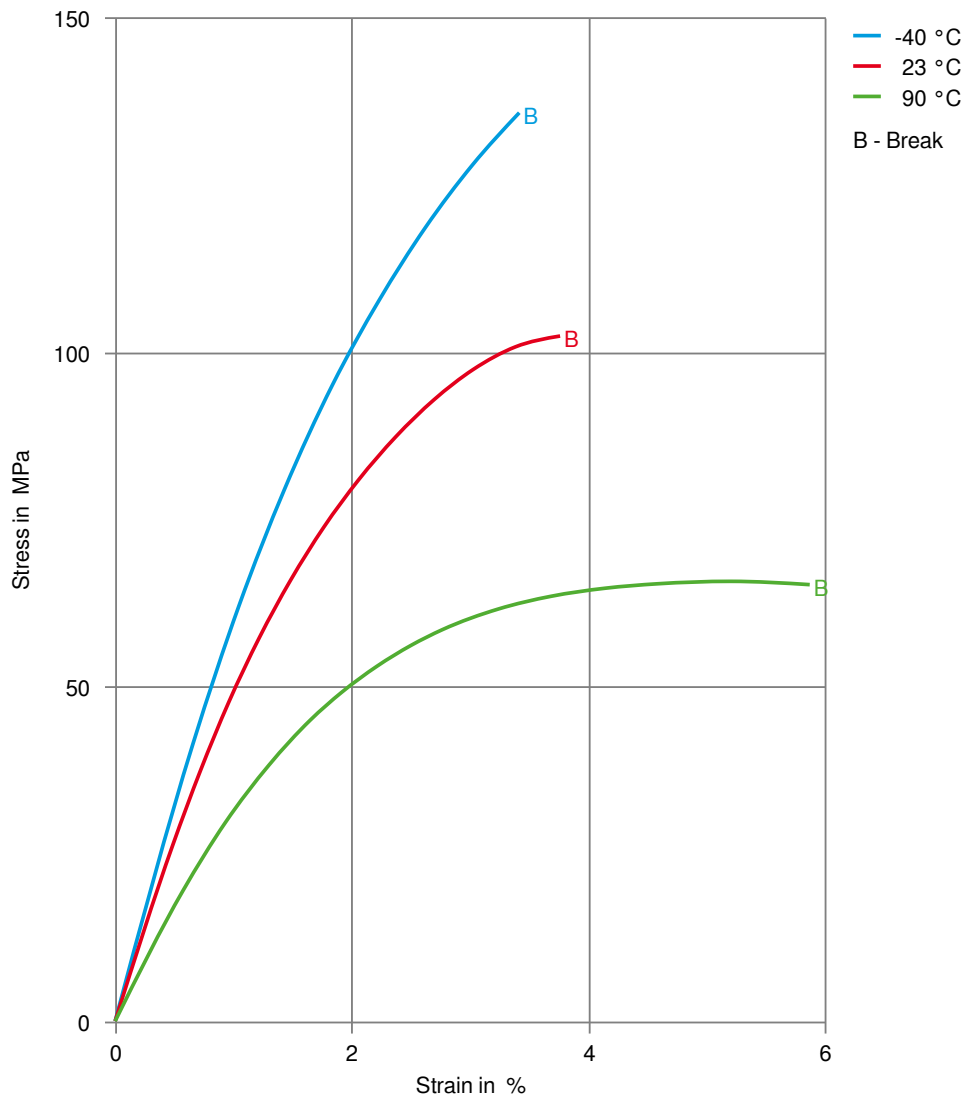
#### Storage

The product can then be stored in standard conditions until processed.

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### Stress-strain



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### Secant modulus-strain

